FX816 Series

DIP4, DC Input, Photo Transistor Coupler

Description

The FX816 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic DIP4 package with different lead forming options.

With the robust coplanar double mold structure, FX816 series provide the most stable isolation feature.

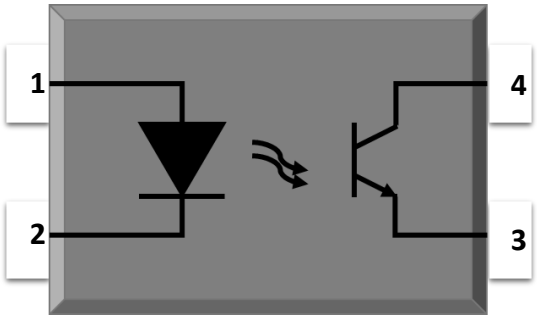
Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- Copper Leadframe
- REACH Compliance
- MSL class 1
- Halogen free (Optional)
- Regulatory Approval
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC - GB4943.1, GB8898

Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

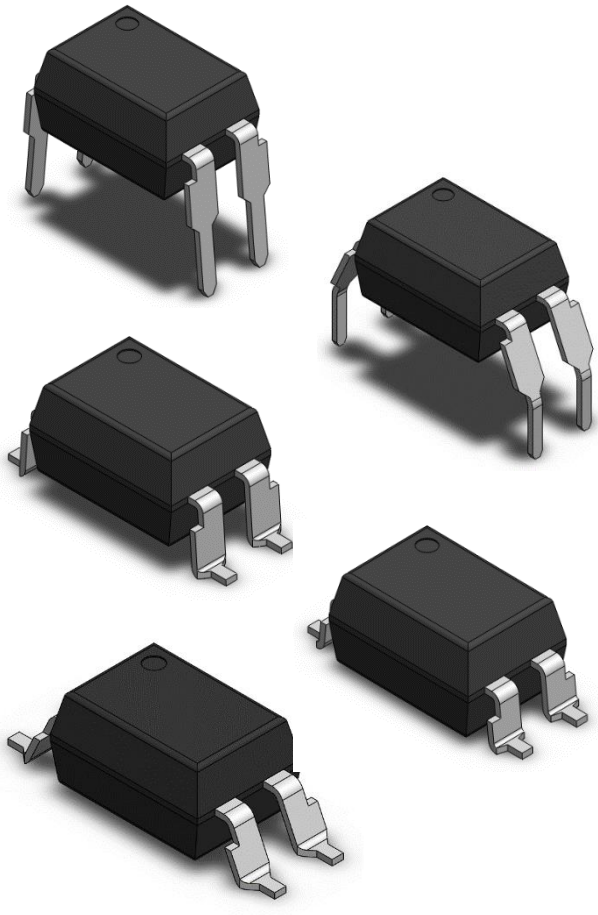
SCHEMATIC



PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

PACKAGE OUTLINE



DIP4, DC Input, Photo Transistor Coupler

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	80	V	
Emitter - Collector Voltage	V_{ECO}	6	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	Ptot	200	mW	
Isolation Voltage	Viso	5000	Vrms	2
Operating Temperature	Topr	-55~110	°C	
Storage Temperature	Tstg	-55~125	°C	
Soldering Temperature	Tsol	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

DIP4, DC Input, Photo Transistor Coupler

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C								
PARAMETER		SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT								
Forward Voltage		V_F	-	1.24	1.4	V	IF=10mA	
Reverse Current		I_R	-	-	10	μA	VR=6V	
Input Capacitance		Cin	-	10	-	pF	V=0, f=1kHz	
OUTPUT								
Collector Dark Current		I_{CEO}	-	-	100	nA	VCE=20V, IF=0	
Collector-Emitter Breakdown Voltage		BV_{CEO}	80	-	-	V	IC=0.1mA, IF=0	
Emitter-Collector Breakdown Voltage		BV_{ECO}	6	-	-	V	IE=0.1mA, IF=0	
TRANSFER CHARACTERISTICS								
Current Transfer Ratio	FX816A	CTR	80	-	160	%	IF=5mA, VCE=5V	
	FX816B		130	-	260			
	FX816C		200	-	400			
	FX816D		300	-	600			
Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	-	0.06	0.2	V	IF=20mA, IC=1mA	
Isolation Resistance		R_{ISO}	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance		C_{IO}	-	0.4	1	pF	V=0, f=1MHz	
Response Time (Rise)		tr	-	3	18	μs	VCE=2V, IC=2mA RL=100Ω	3
Response Time (Fall)		tf	-	4	18	μs		3
Cut-off Frequency		fc	-	80	-	kHz	VCE=2V, IC=2mA RL=100Ω,-3dB	4

Note 3. Fig.12&13

Note 4. Fig.14

DIP4, DC Input, Photo Transistor Coupler

CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

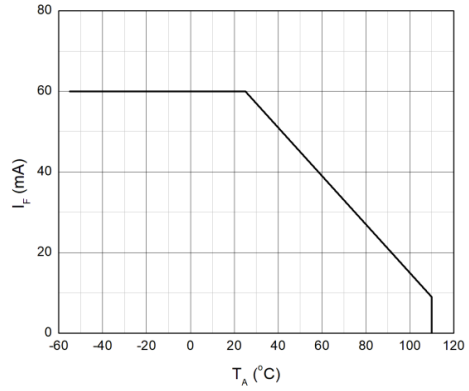


Fig.2 Collector Power Dissipation vs. Ambient Temperature

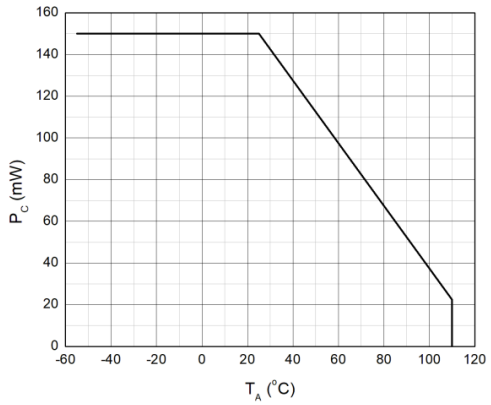


Fig.3 Forward Current vs. Forward Voltage

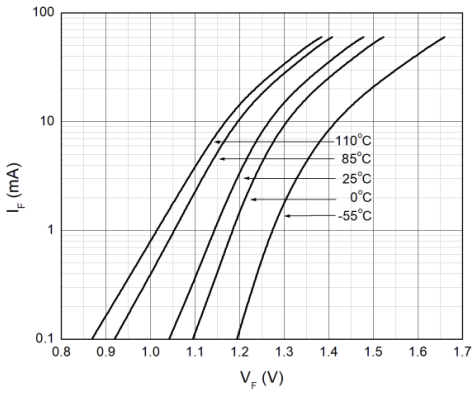


Fig.4 Collector Dark Current vs. Ambient Temperature

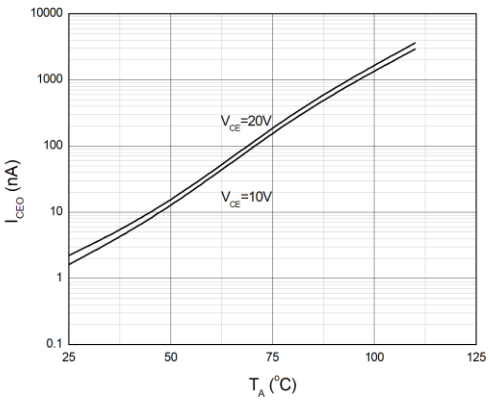


Fig.5 Collector Current vs. Collector-emitter Voltage

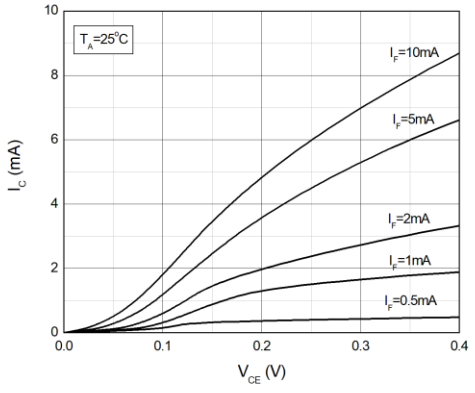
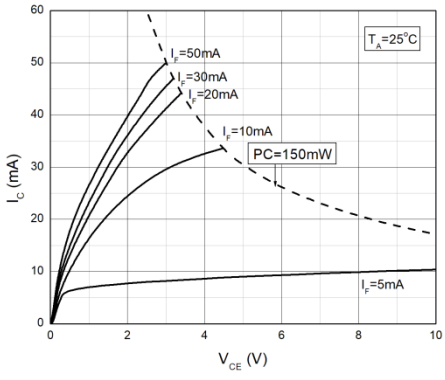


Fig.6 Collector Current vs. Collector-emitter Voltage



CHARACTERISTIC CURVES

Fig.7 Normalized Current Transfer Ratio vs. Forward Current

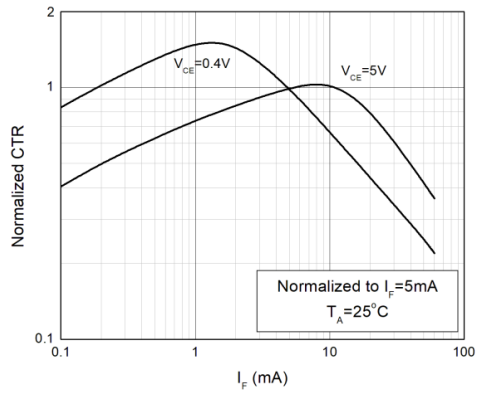


Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature

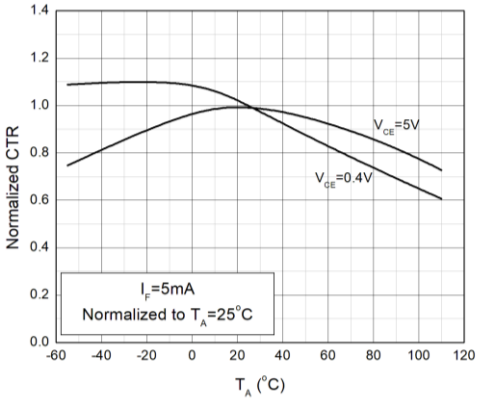


Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature

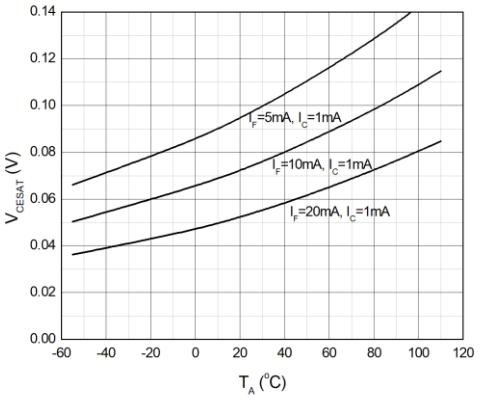


Fig.10 Switching Time vs. Load Resistance

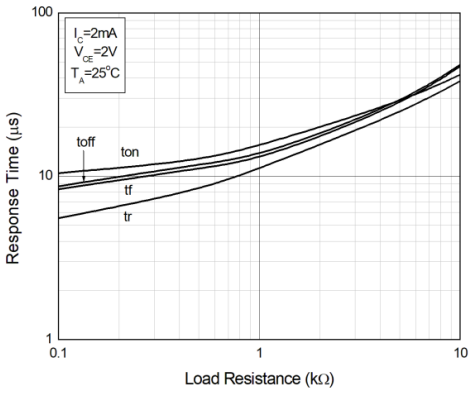
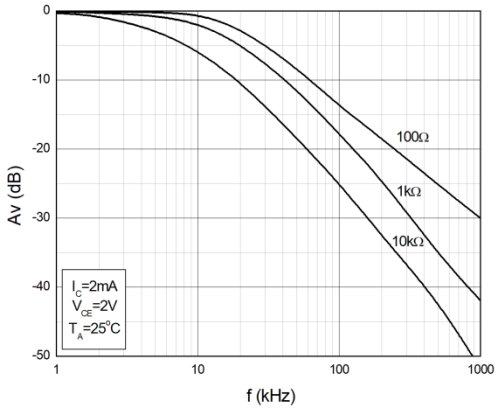


Fig.11 Frequency Response



TEST CIRCUITS

Fig.12 Test Circuits of Response Time

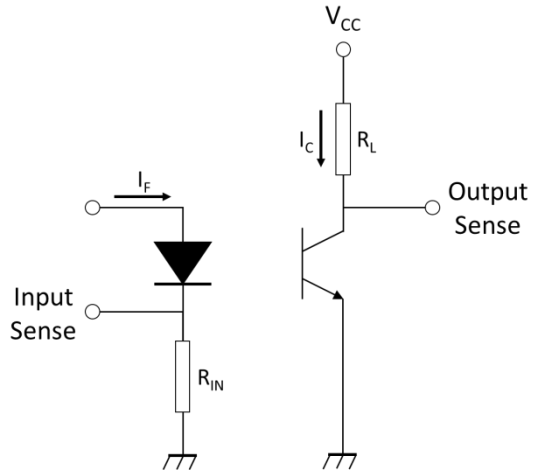


Fig.13 Curves of Response Time

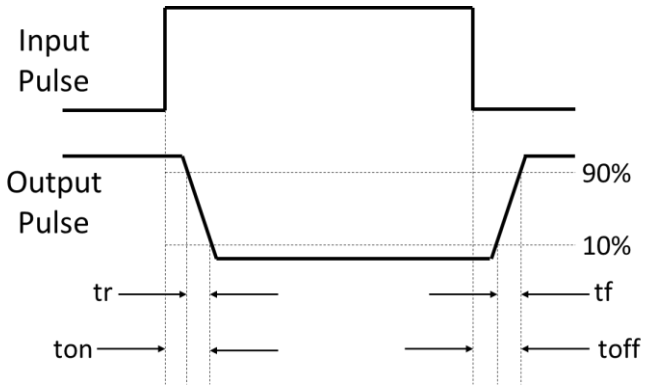
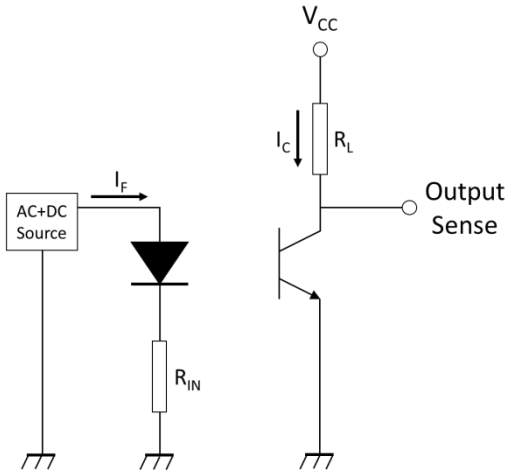


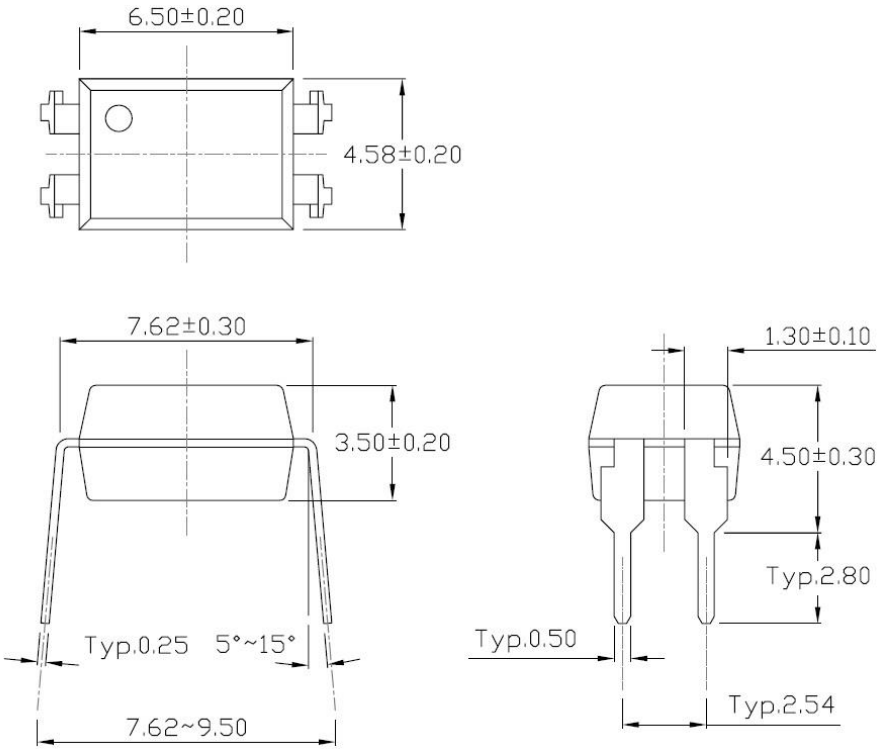
Fig.14 Test Circuits of Frequency Response



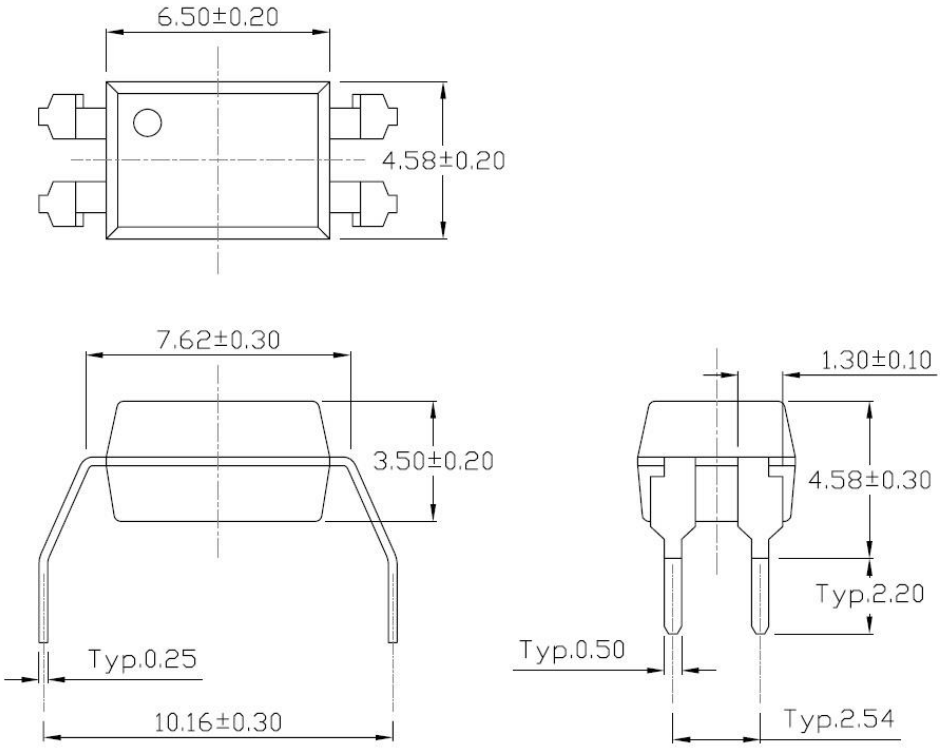
DIP4, DC Input, Photo Transistor Coupler

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP – Through Hole (N Type)



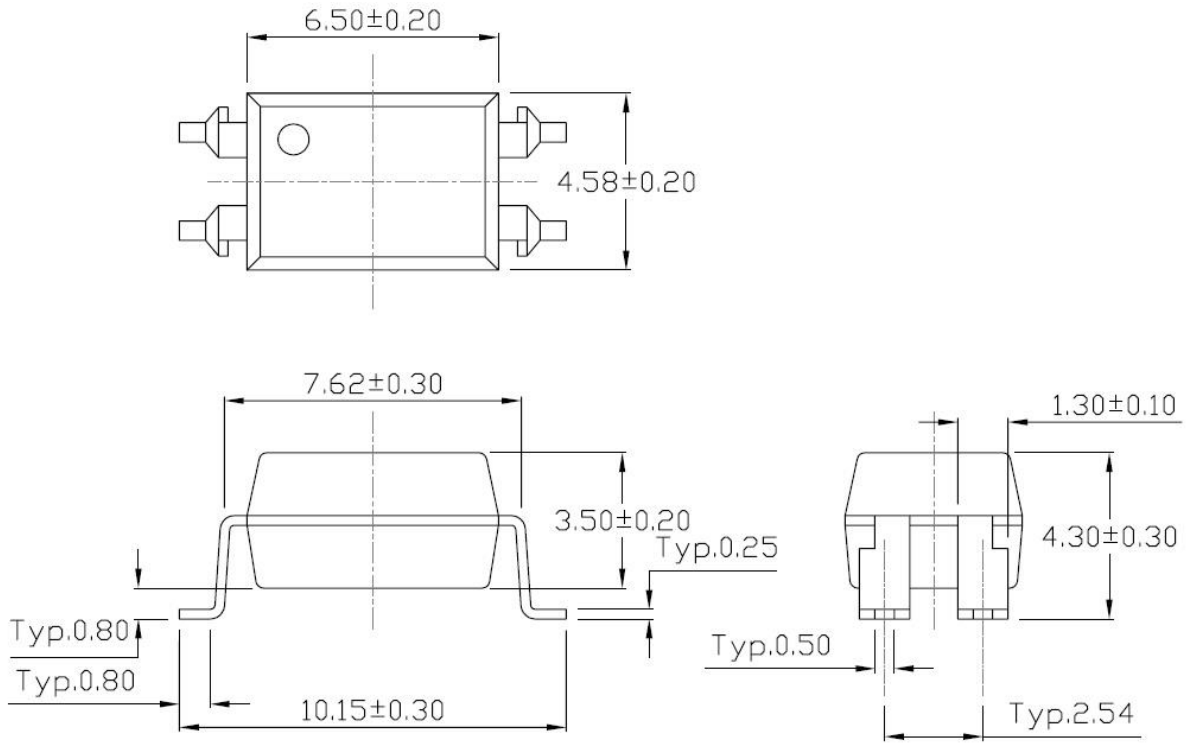
Gullwing (400mil) Lead Forming – Through Hole (M Type)



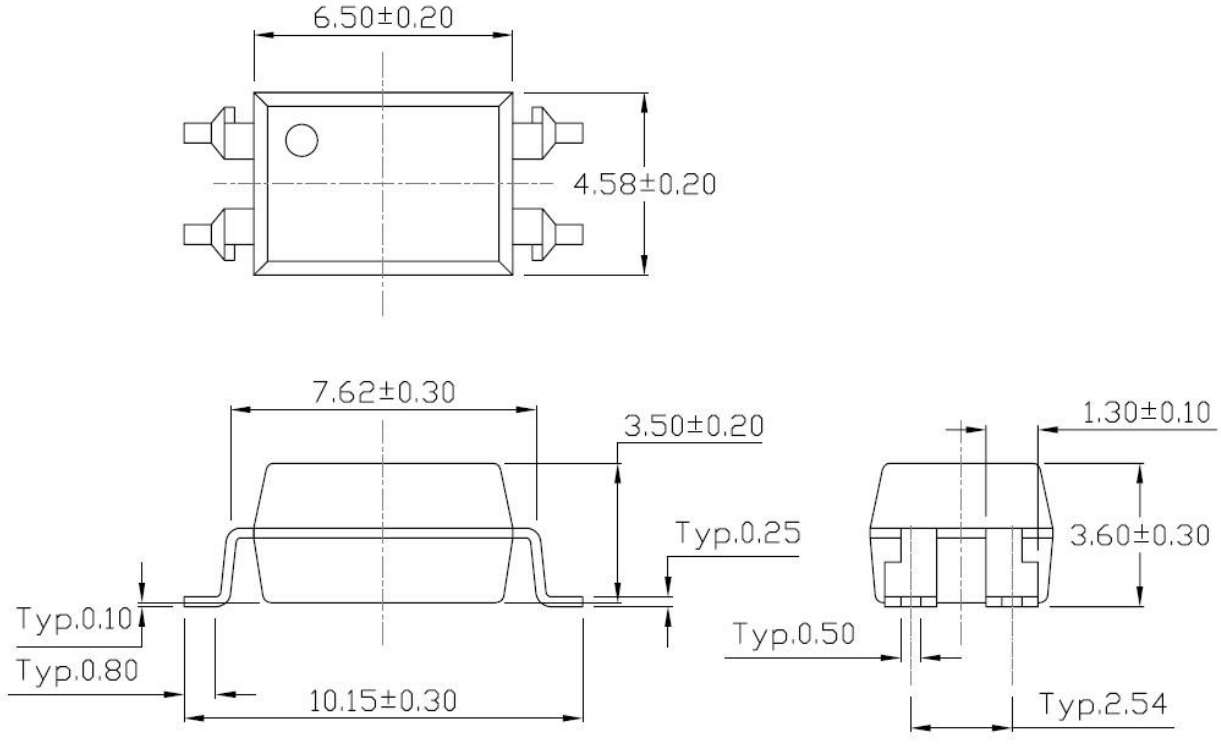
DIP4, DC Input, Photo Transistor Coupler

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming (S Type)



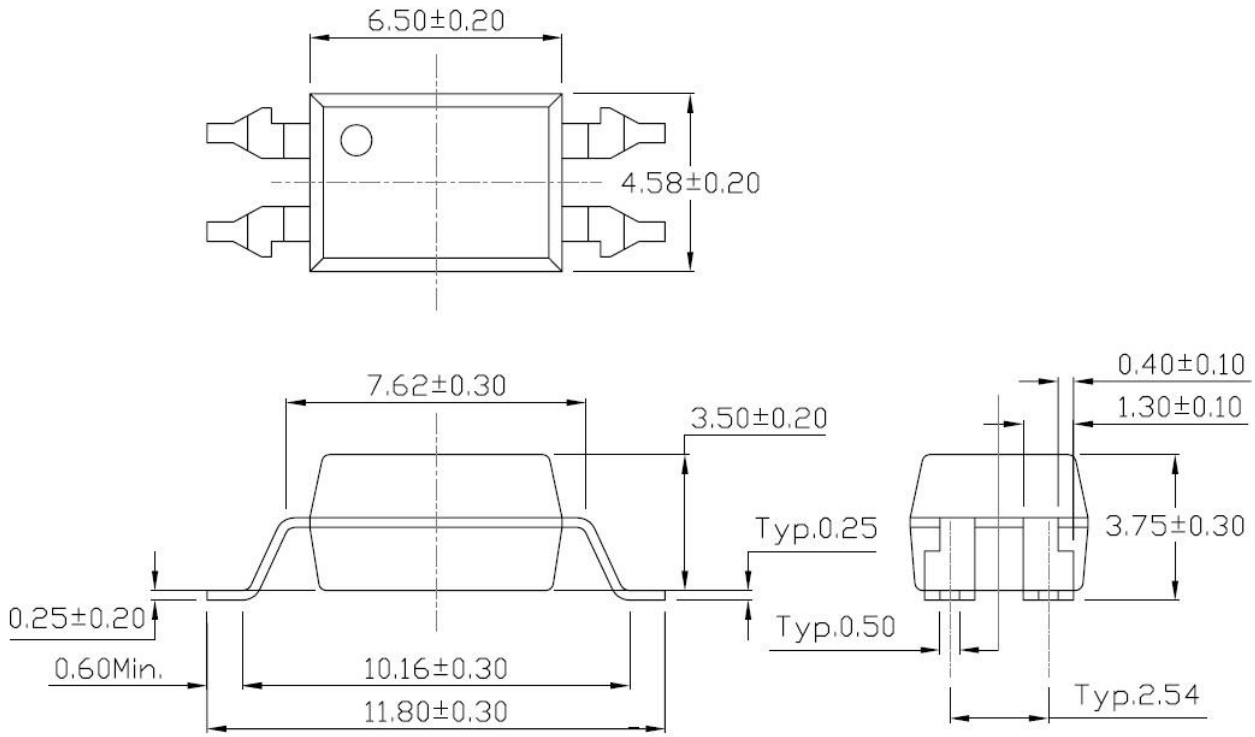
Surface Mount (Low Profile) Lead Forming (T Type)



DIP4, DC Input, Photo Transistor Coupler

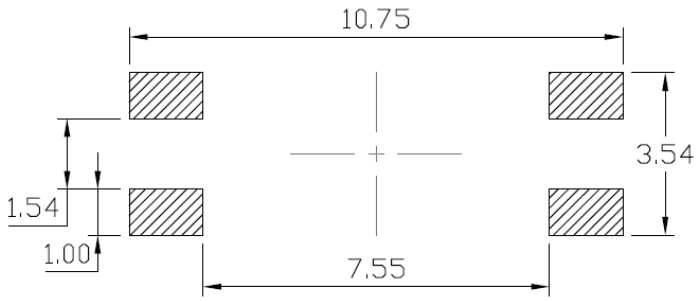
PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount (Gullwing) Lead Forming (U Type)

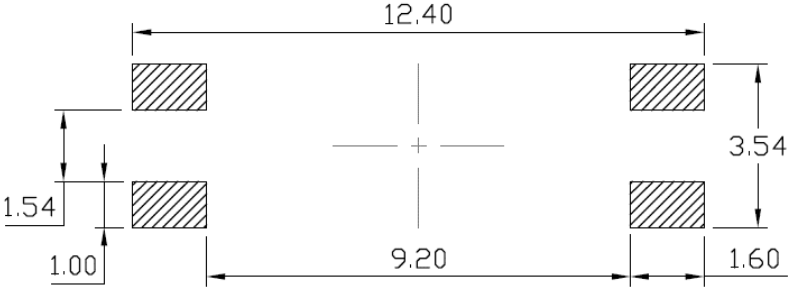


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



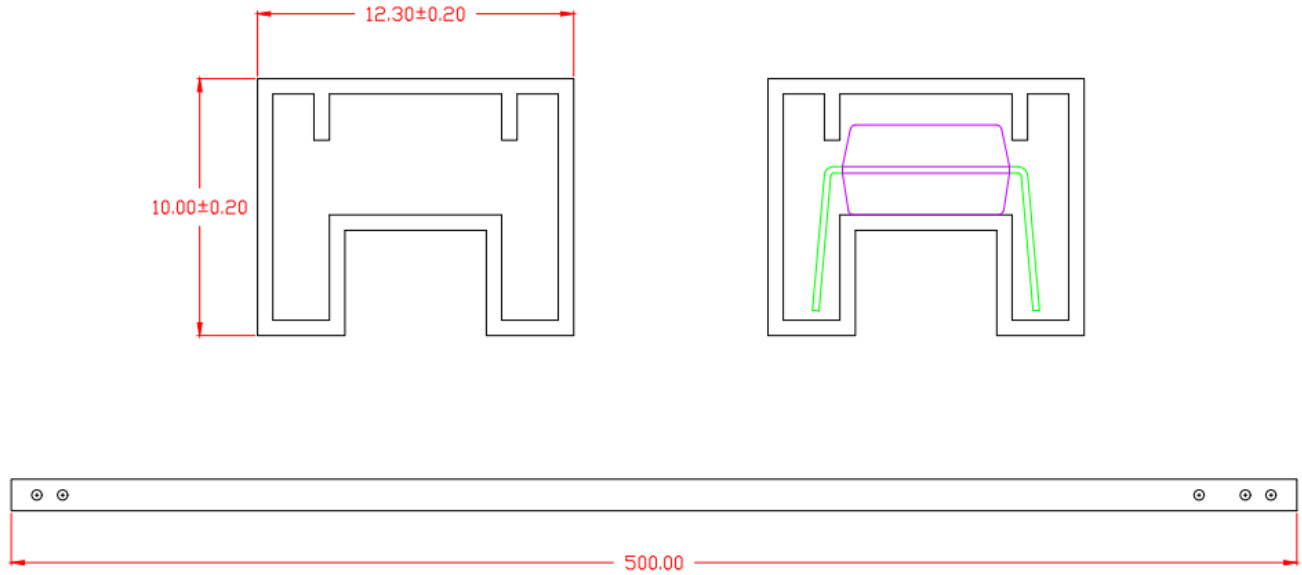
Surface Mount (Gullwing) Lead Forming



DIP4, DC Input, Photo Transistor Coupler

TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

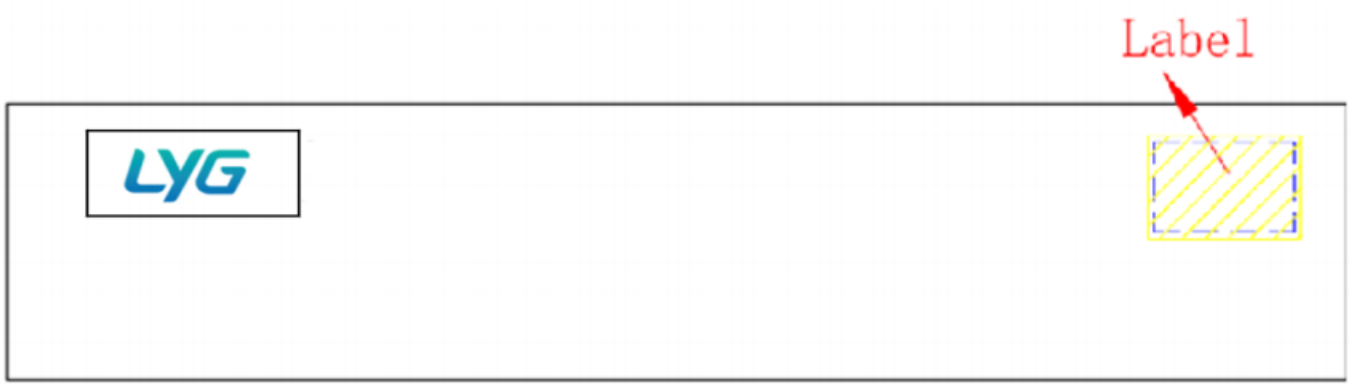
Packing Option 0 for N / M Type



DIP4, DC Input, Photo Transistor Coupler

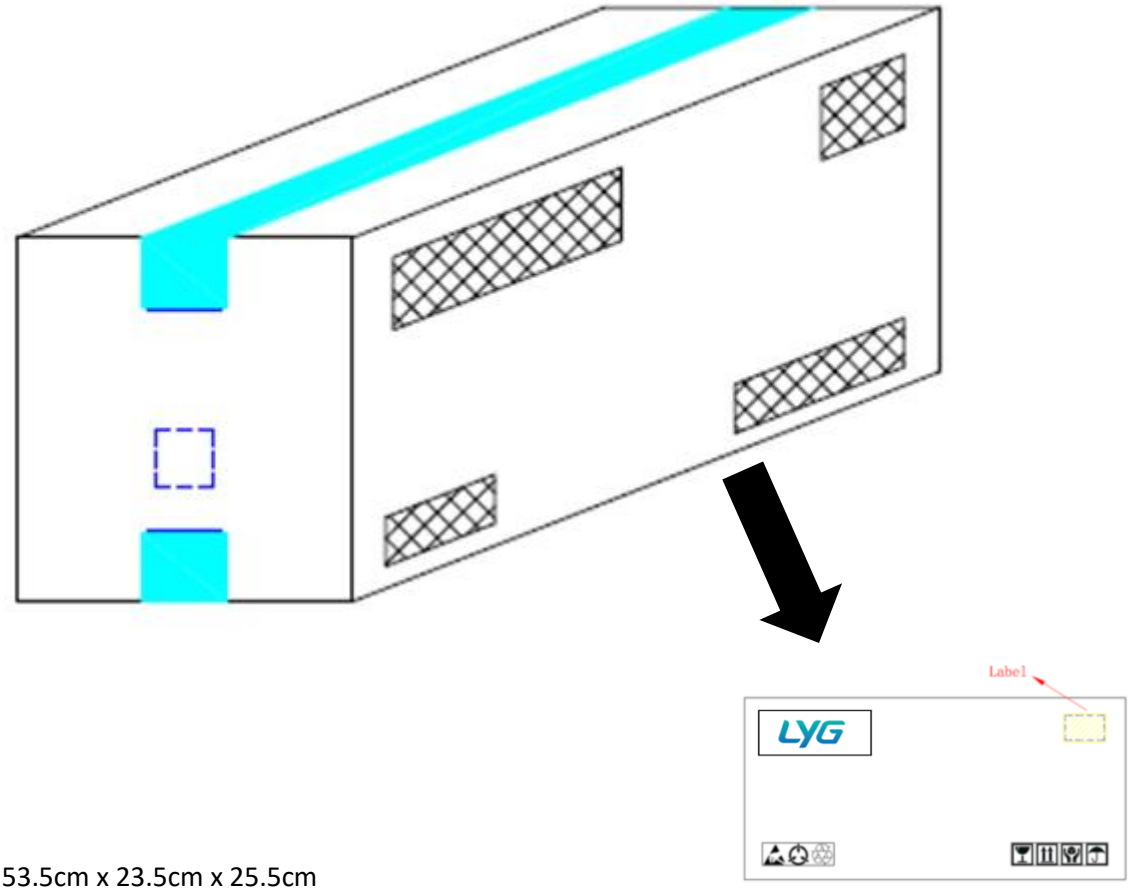
BOX SPECIFICATIONS (Tube Type)

Inner Box



- L x W x H = 52.5cm x 10.7cm x 4.7cm

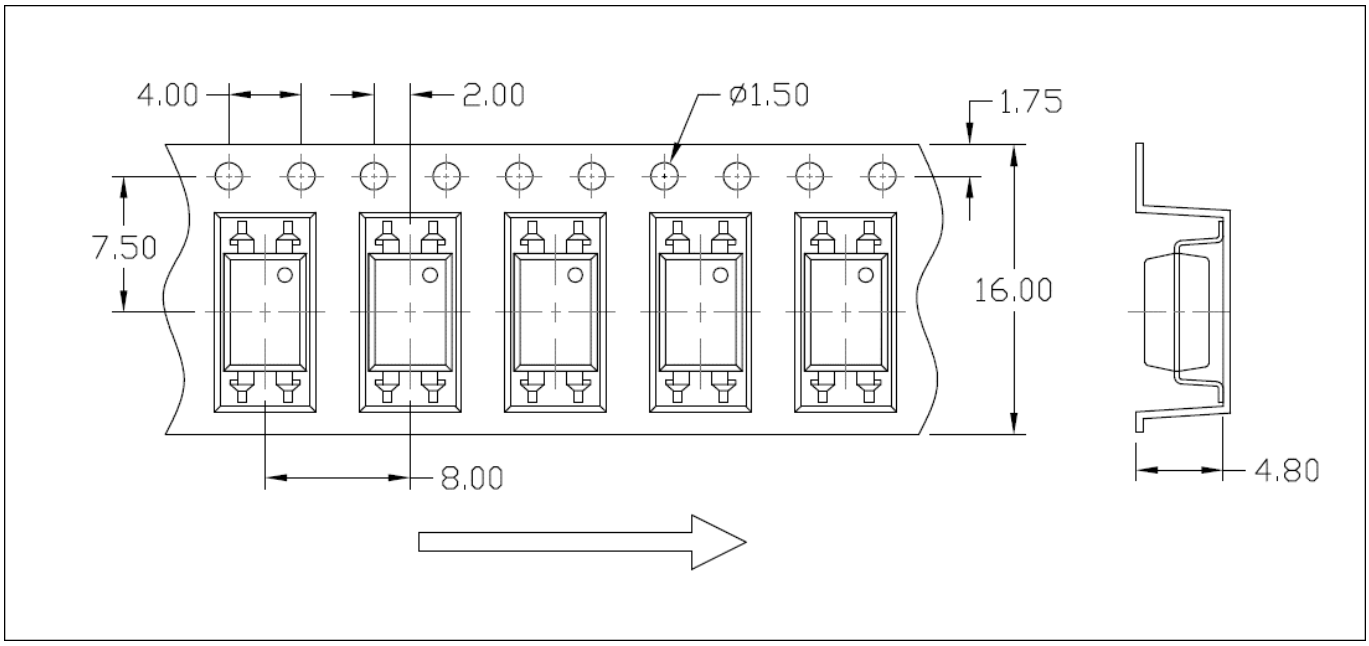
Outer Box



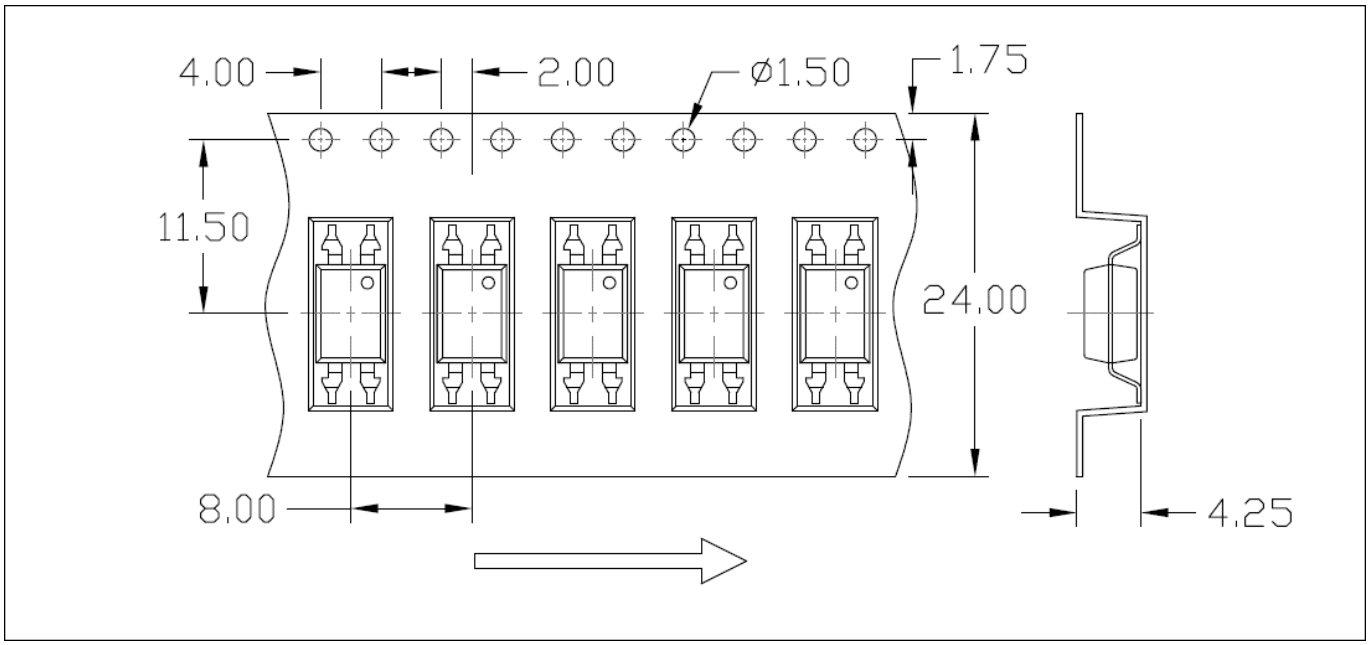
- L x W x H = 53.5cm x 23.5cm x 25.5cm

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Packing Option 1 for S / T Type



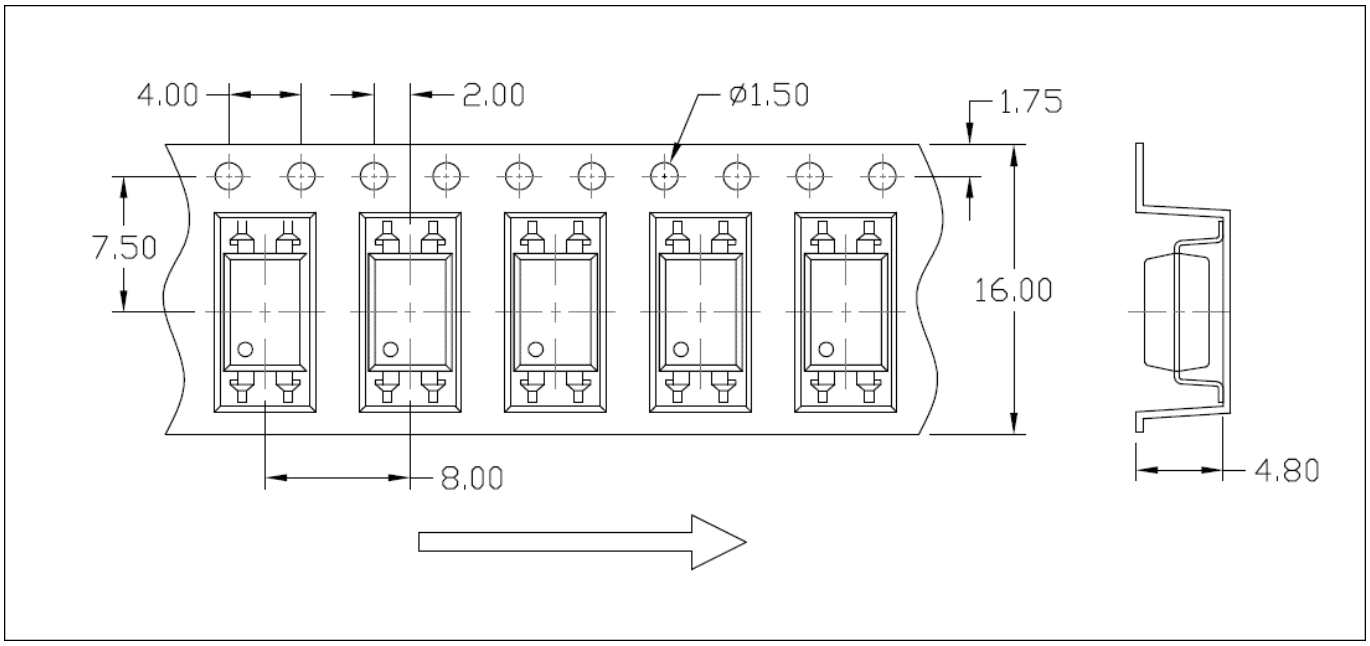
Packing Option 1 for U Type



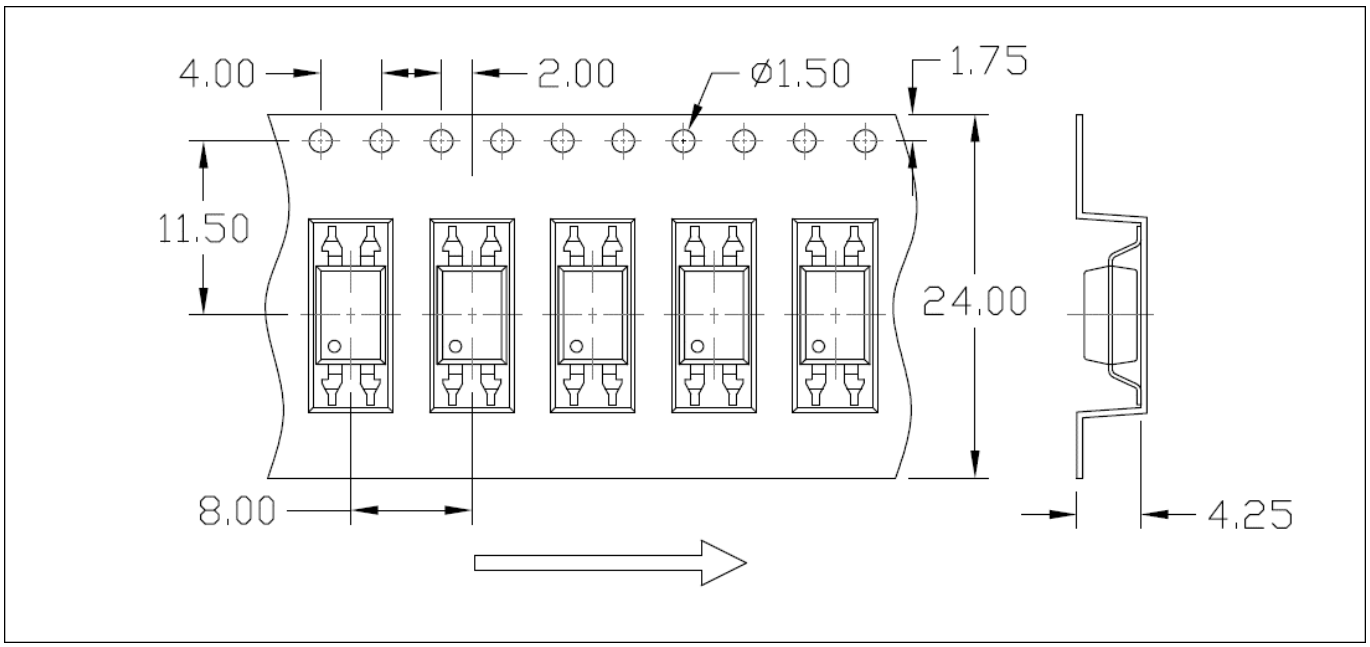
DIP4, DC Input, Photo Transistor Coupler

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Packing Option 2 for S / T Type



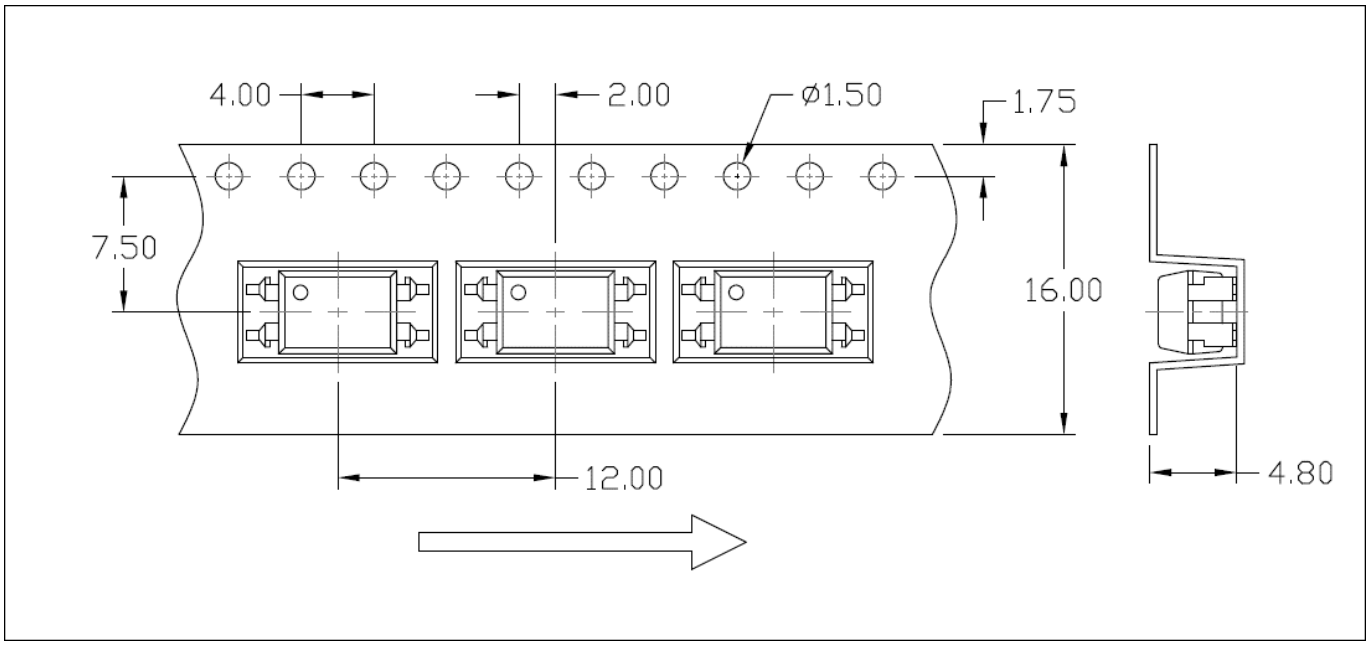
Packing Option 2 for U Type



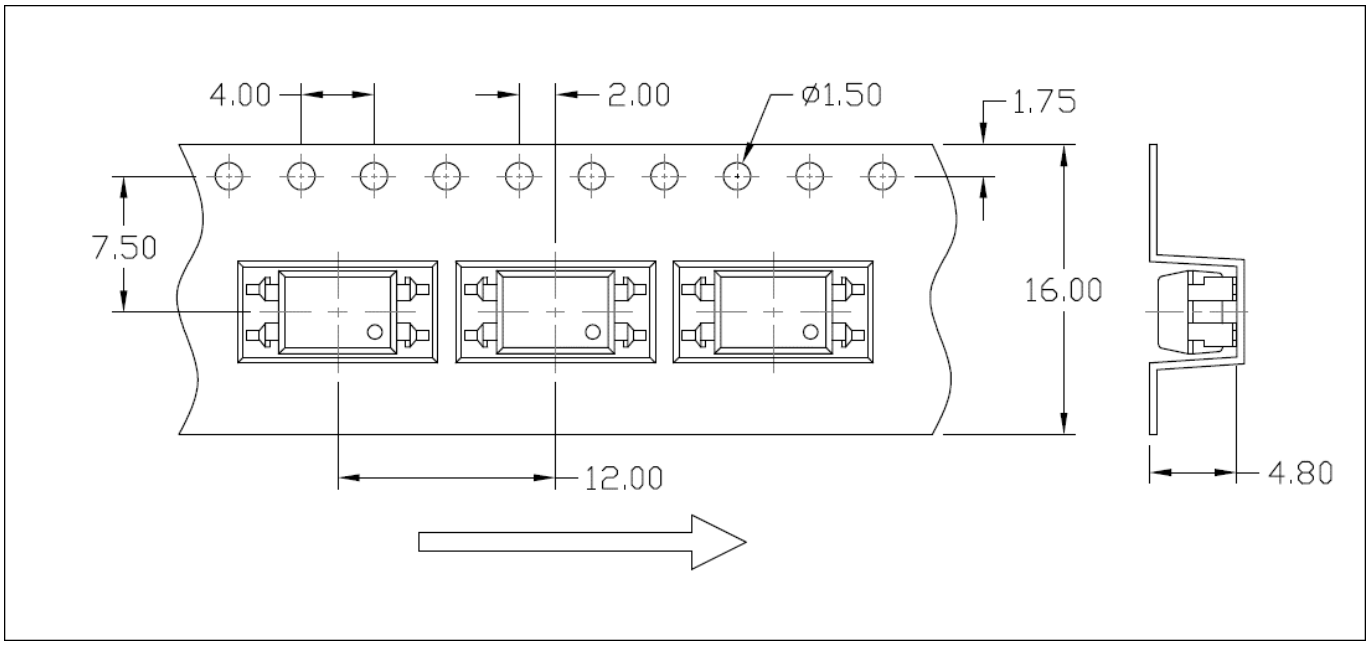
DIP4, DC Input, Photo Transistor Coupler

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Packing Option 3 for S / T Type



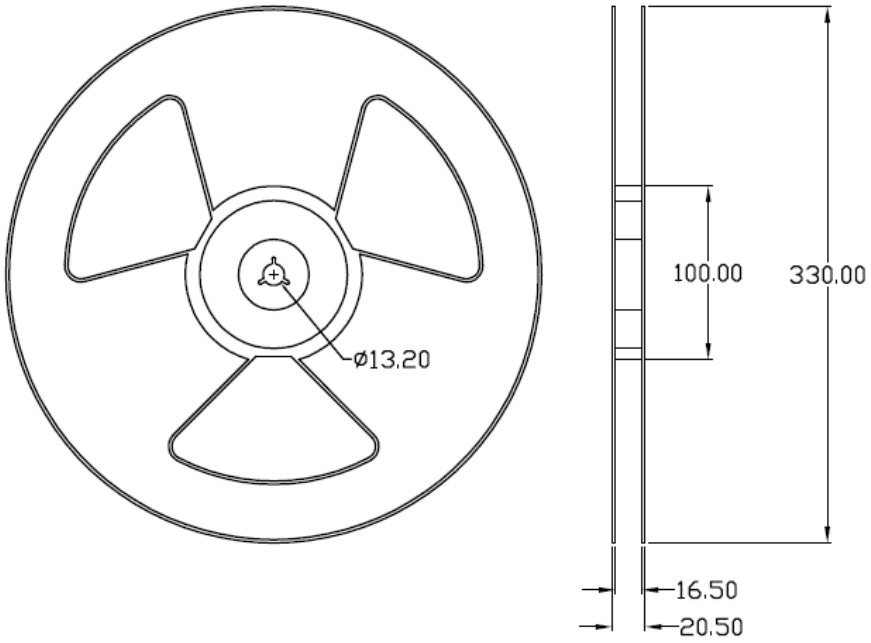
Packing Option 4 for S / T Type



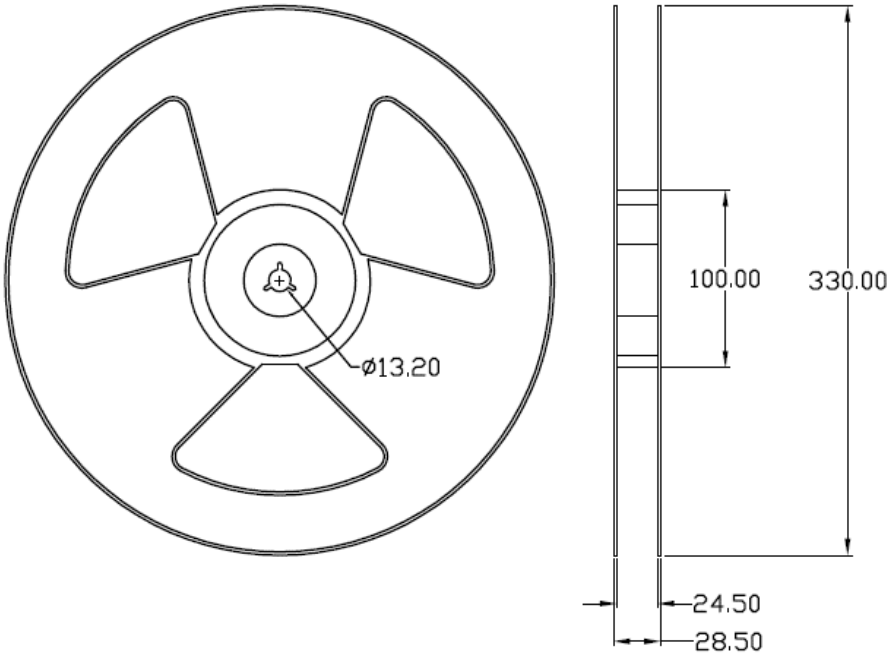
DIP4, DC Input, Photo Transistor Coupler

REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Reel Dimension for S / T Type



Reel Dimension for U Type



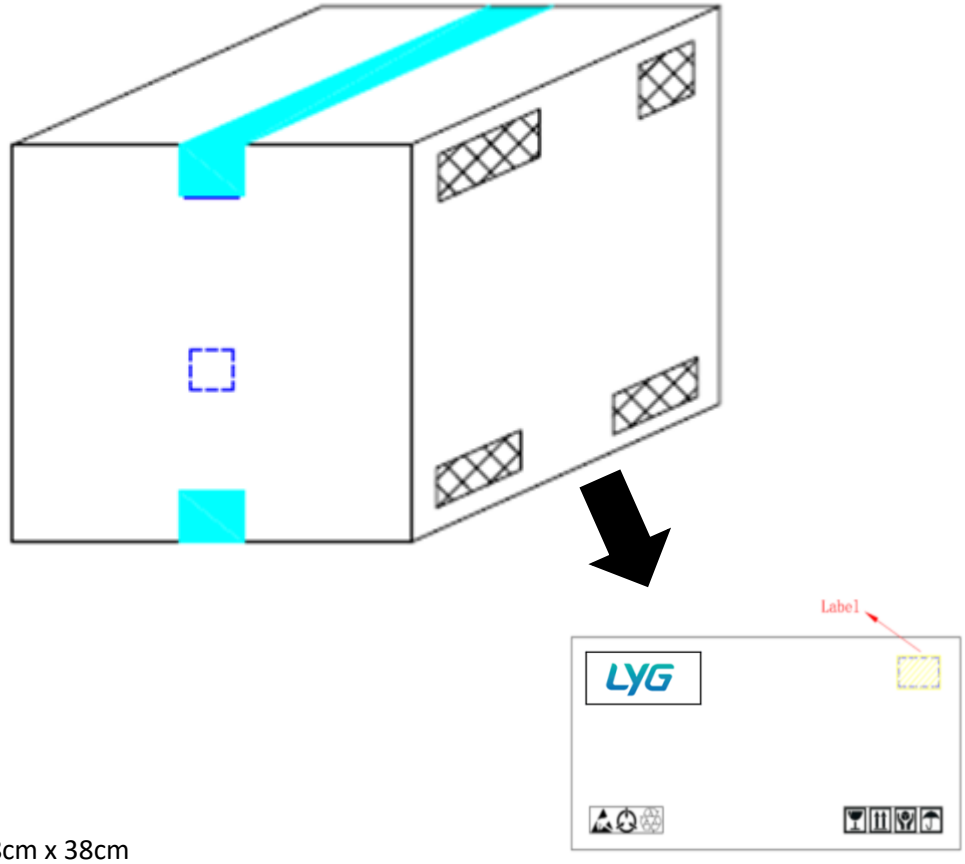
DIP4, DC Input, Photo Transistor Coupler

BOX SPECIFICATIONS (Reel Type)

Inner Box

- L x W x H = 36cm x 36cm x 6.9cm

Outer Box



- L x W x H = 45cm x 38cm x 38cm

DIP4, DC Input, Photo Transistor Coupler

ORDERING AND MARKING INFORMATION

MARKING INFORMATION

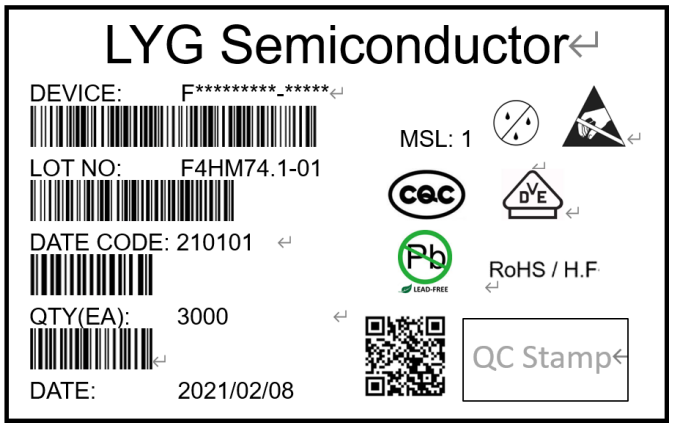
LYG : Company Abbr.
FX816 : Part Number
R : CTR Rank Option
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

FX816RVBTH-LZP1GC

FX816 – Part Number
R – Rank Option (A/B/C/D)
V – VDE Option (V or N)
BTH – Fixed Character
L – Lead Form Type (N/M/S/T/U)
Z – Packing Option (0/1/2/3/4)
P1 – Fixed Character
G – Halogen free (G or None)
C – Color Option (B or W)

LABEL INFORMATION

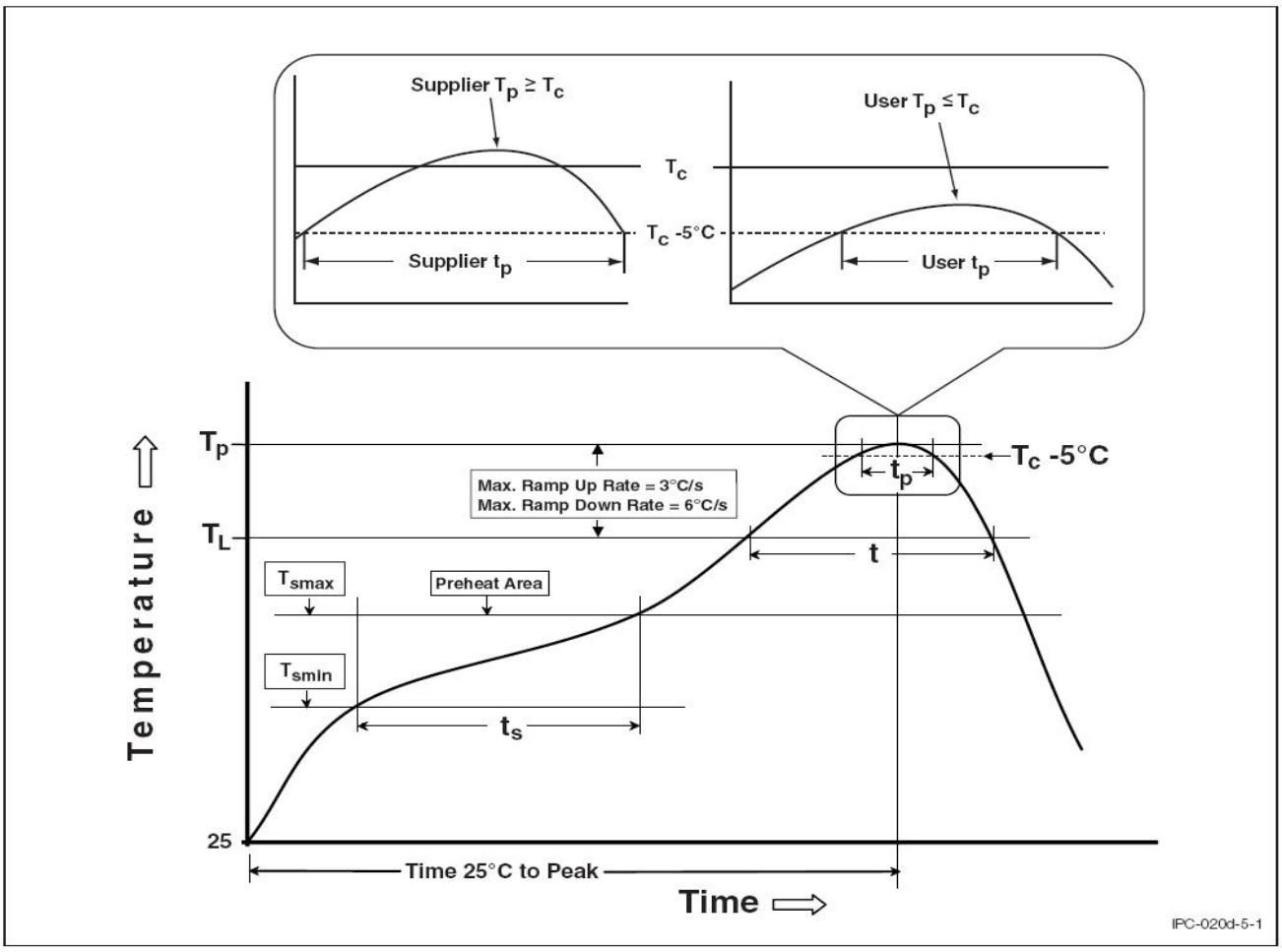


Packing Quantity

Option	Quantity	Quantity – Inner box	Quantity – Outer box
N0	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units
M0	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units
S1	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
S2	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
S3	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
S4	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
T1	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
T2	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
T3	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
T4	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
U1	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
U2	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units

REFLOW INFORMATION

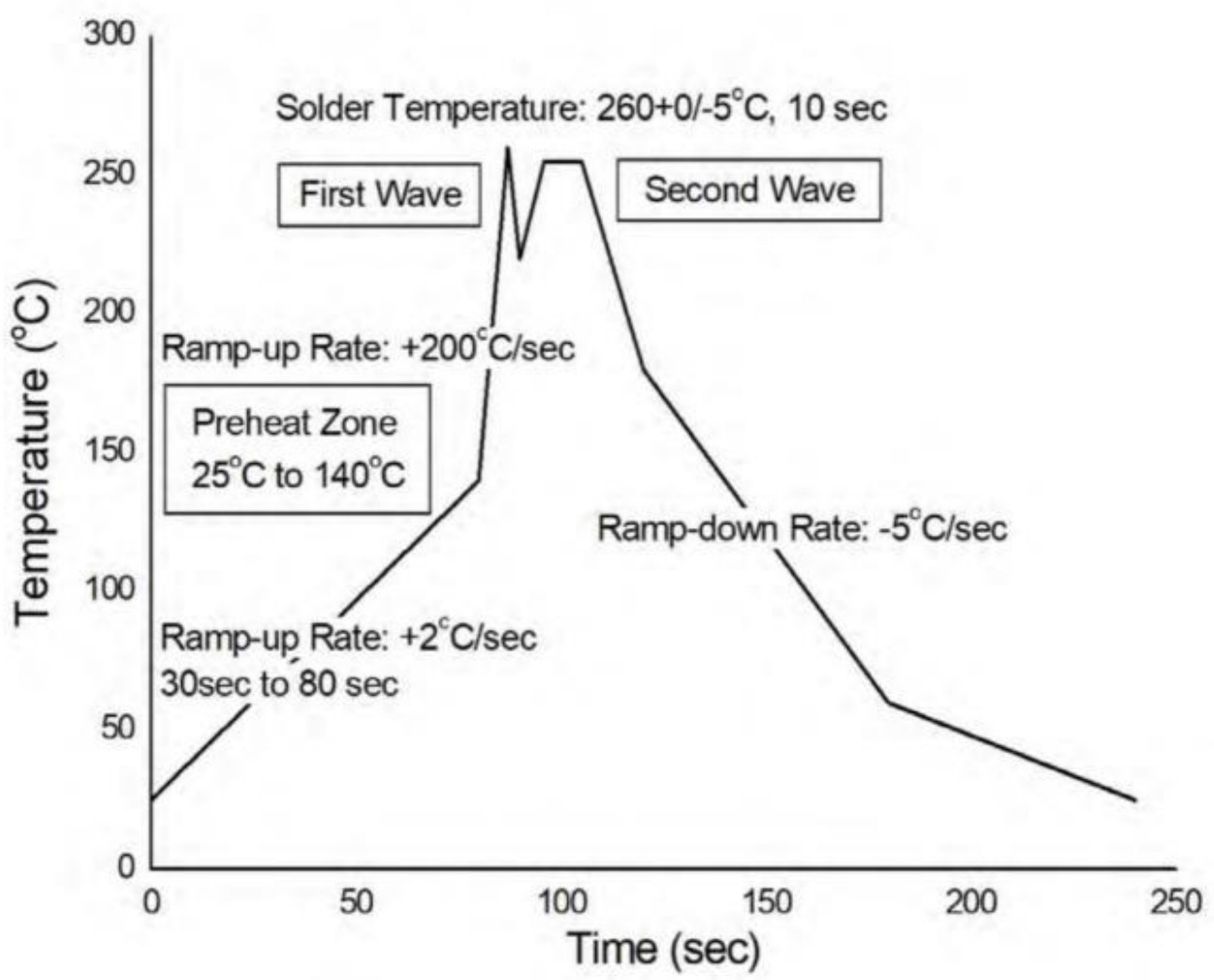
REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

TEMPERATURE PROFILE OF SOLDERING

WAVE SOLDERING(JESD22-A111 COMPLIANT)



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

DIP4, DC Input, Photo Transistor Coupler

DISCLAIMER

- LYG is continually improving the quality, reliability, function and design. LYG reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- LYG makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, LYG disclaims (a) any and all liability arising out of the application or use of any product, (b) any and all liability, including without limitation special, consequential or incidental damages, and (c) any and all implied warranties, including warranties of fitness for particular
- The products shown in this publication are designed for the general use in electronic applications such as office automation, equipment, communications devices, audio/visual equipment, electrical application and instrumentation purpose, non-infringement and merchantability.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact LYG sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify LYG's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.